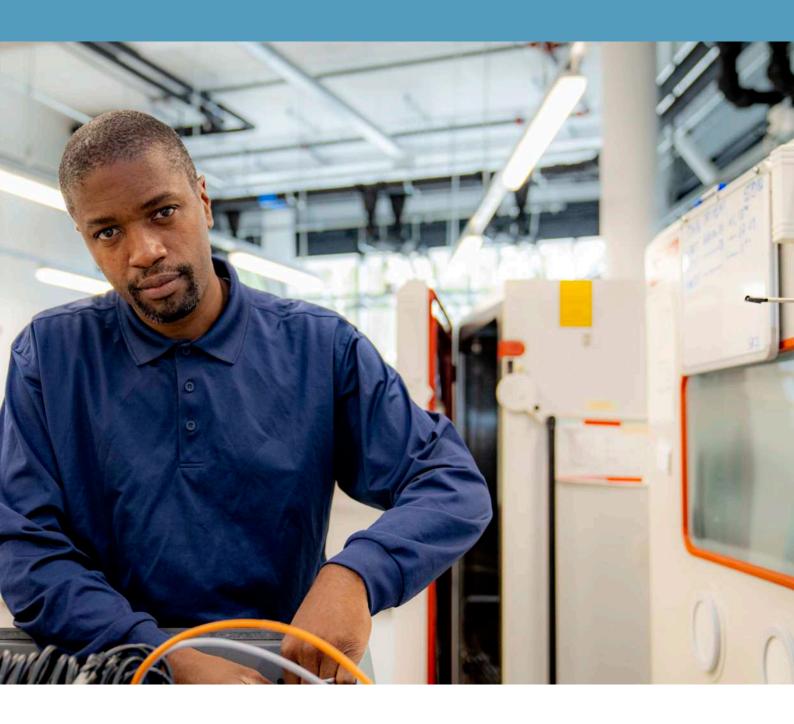




Thermal shock testing

Nemko Norway



Thermal shock testing exposes your products to two extreme air temperatures with a rapid transition between. Such exposure will test the expansion rates of parts and components, and the bonding strength of various materials.

Repeated exposure can lead to material fatigue, weakening of bonds, cracks, ruptures and peeling of coating.

Find potential design and production faults within a product that would be caused by expansion and contractions of parts and components due to temperature variations. When done in the development phase of a product it will be cost effective while improving its durability and robustness, and help you deliver a more reliable end product and can help maintain compliance.

Thermal shocking is used commonly to evaluate and check the following:

- Evaluating PCB mounting reliability after a change in lead-free solder or another connection material
- Evaluating reliability after a change in mounting format such as BGA or CSP
- Evaluating connection resistance by connector temperature variation
- Checking for cracks by thermal deformation of molded plastic parts
- Checking for cracking, peeling or seal leaks in bonded materials
- Evaluating combinations of different material types such as plastic with inserted nuts
- Screening processes before product shipment

Nemko uses both single and multiple chamber to perform the thermal shock tests, depending on the size of the product. Small and medium sized products are tested in multiple chambers, with separate hot and cold chambers and an elevator between them, which results in more rapid rate of temperature changes.

Specifications

Hot chamber: + 50 °C / + 200 °C
Cold chamber: -80 °C / +100 °C

• Transtion Time: ≥ 10s

• Temperature range change: Up to 100 kelvin in one minute

Space: 32 Liters
Height: 300mm
Width: 360mm
Depth: 300mm

Involve Nemko early in the process to avoid delay to market and excessive cost.



